

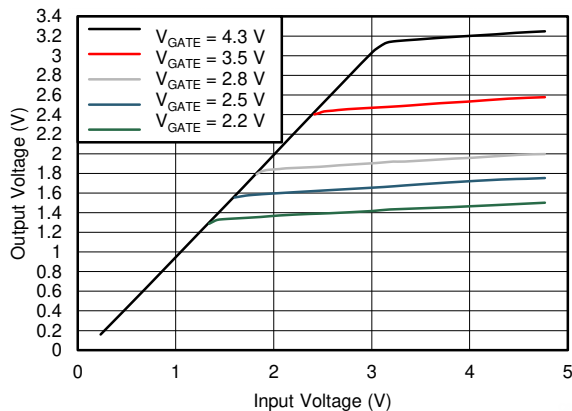
TXS0104E-Q1 用于开漏和推挽应用的汽车级 4 位双向电压电平转换器

1 特性

- 符合汽车应用要求
- 具有符合 AEC-Q100 标准的下列特性：
 - 器件温度等级 1：-40°C 至 +125°C 环境温度范围
 - 器件 HBM ESD 分类等级 2
 - 器件 CDM ESD 分类等级 C6
- 无需方向控制信号
- 最大数据速率：
 - 最大值 24Mbps (推挽)
 - 2Mbps (开漏)
- A 端口支持 1.65V 至 3.6V 的电压，B 端口支持 2.3V 至 5.5V 的电压 ($V_{CCA} \leq V_{CCB}$)
- 无需电源时序控制 — V_{CCA} 或 V_{CCB} 均可优先斜升
- 静电放电 (ESD) 保护性能超过 JESD 22 规范要求：
 - A 端口
 - 2000V 人体放电模型 (A114-B)
 - 1000V 充电器件模型 (C101)
 - B 端口
 - 15kV 人体放电模型 (A114-B)
 - 1000V 充电器件模型 (C101)
- IEC 61000-4-2 ESD (B 端口)
 - ±8kV 接触放电
 - ±10kV 气隙放电

2 应用

- 汽车信息娱乐系统，高级驾驶辅助系统 (ADAS)
- 在主处理器和外设模块间进行隔离和电平转换
- I²C 或 1 线制电压电平转换



N 沟道晶体管的传输特征

3 说明

由于电压不匹配，TXS0104E-Q1 器件连接芯片与芯片间的非兼容逻辑通信。这款自动导向转换器可方便地用来在无需主机方向控制的情况下缩小之间的差距。在无需主机干预的情况下，每个通道可混合使用，并且可以与不同的输出类型（开漏或推挽）和混合数据流（发送或接收）相匹配。这个 4 位非反向转换器使用两个独立的可配置电源轨。A 和 B 端口被设计用来分别跟踪 V_{CCA} 和 V_{CCB} 。 V_{CCB} 引脚在 V_{CCA} 引脚接受 1.65V 至 3.6V 之间的任一电源电压的同时，接受 2.3V 至 5.5V 之间的任何电源电压，这样的话， V_{CCA} 小于或等于 V_{CCB} 。这个跟踪功能可实现 1.8V，2.5V，3.3V 和 5V 电压节点之间的低电压双向转换。

当输出使能端 (OE) 输入为低电平时，所有输出都被置于高阻抗状态。

TXS0104E-Q1 器件被设计成 OE 输入电路由 V_{CCA} 供电。

为了在加电或断电期间处于高阻抗状态，OE 引脚必须通过一个下拉电阻接到 GND 引脚；此电阻的最小值由驱动器的拉电流能力决定。

封装信息

器件型号	封装 ⁽¹⁾	封装尺寸 ⁽²⁾
TXS0104E-Q1	PW (TSSOP, 14)	5mm × 6.4mm
	BQA (WQFN, 14)	3mm × 2.5mm
	RUT (UQFN, 12)	2mm × 1.7mm

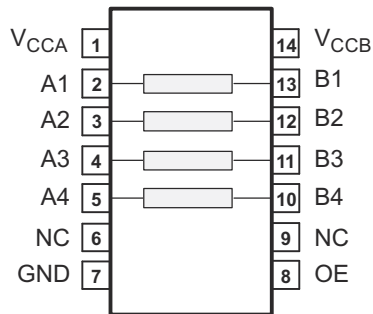
- 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。
- 封装尺寸 (长 × 宽) 为标称值，并包括引脚 (如适用)。



Table of Contents

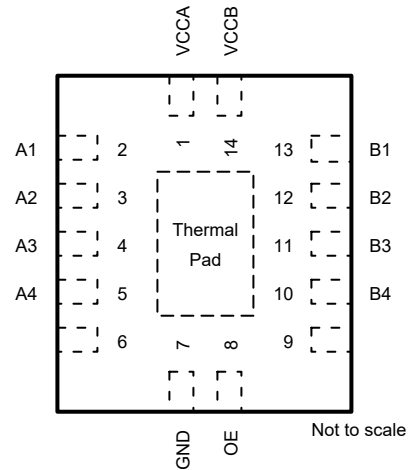
1 特性	1	7 Detailed Description	16
2 应用	1	7.1 Overview.....	16
3 说明	1	7.2 Functional Block Diagram.....	16
4 Pin Configuration and Functions	3	7.3 Feature Description.....	17
5 Specifications	5	7.4 Device Functional Modes.....	17
5.1 Absolute Maximum Ratings.....	5	8 Application and Implementation	18
5.2 ESD Ratings.....	5	8.1 Application Information.....	18
5.3 Recommended Operating Conditions.....	5	8.2 Typical Application.....	18
5.4 Thermal Information.....	6	8.3 Power Supply Recommendations.....	19
5.5 Electrical Characteristics.....	6	8.4 Layout.....	20
5.6 Timing Requirements— $V_{CCA} = 1.8\text{ V} \pm 0.15\text{ V}$	7	9 Device and Documentation Support	21
5.7 Timing Requirements— $V_{CCA} = 2.5\text{ V} \pm 0.2\text{ V}$	7	9.1 Documentation Support.....	21
5.8 Timing Requirements— $V_{CCA} = 3.3\text{ V} \pm 0.3\text{ V}$	7	9.2 接收文档更新通知.....	21
5.9 Switching Characteristics— $V_{CCA} = 1.8\text{ V} \pm 0.15\text{ V}$	8	9.3 支持资源.....	21
5.10 Switching Characteristics— $V_{CCA} = 2.5\text{ V} \pm 0.2\text{ V}$...	10	9.4 Trademarks.....	21
5.11 Switching Characteristics— $V_{CCA} = 3.3\text{ V} \pm 0.3\text{ V}$...	12	10 静电放电警告	21
5.12 Typical Characteristics.....	13	11 术语表	21
6 Parameter Measurement Information	14	12 Revision History	21
6.1 Load Circuits.....	14	13 Mechanical, Packaging, and Orderable Information	22
6.2 Voltage Waveforms.....	15		

4 Pin Configuration and Functions



NC - No internal connection

图 4-1. PW Package, 14-Pin TSSOP (Top View)



NC - No internal connection

图 4-2. BQA Package, 14-Pin WQFN (Top View)

表 4-1. Pin Functions

PIN		TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.		
A1	2	I/O	Input-output 1 for the A port. This pin is referenced to V _{CCA} .
A2	3	I/O	Input-output 2 for the A port. This pin is referenced to V _{CCA} .
A3	4	I/O	Input-output 3 for the A port. This pin is referenced to V _{CCA} .
A4	5	I/O	Input-output 4 for the A port. This pin is referenced to V _{CCA} .
B1	13	I/O	Input-output 1 for the B port. This pin is referenced to V _{CCB} .
B2	12	I/O	Input-output 2 for the B port. This pin is referenced to V _{CCB} .
B3	11	I/O	Input-output 3 for the B port. This pin is referenced to V _{CCB} .
B4	10	I/O	Input-output 4 for the B port. This pin is referenced to V _{CCB} .
GND	7	—	Ground
NC	6	—	No connection
	9		
OE	8	I	Tri-state output-mode enable. Pull the OE pin low to place all outputs in tri-state mode. This pin is referenced to V _{CCA} .
V _{CCA}	1	I	A-port supply voltage. 1.65 V ≤ V _{CCA} ≤ 3.6 V and V _{CCA} ≤ V _{CCB} .
V _{CCB}	14	I	B-port supply voltage. 2.3 V ≤ V _{CCB} ≤ 5.5 V.

(1) I = input, O = output

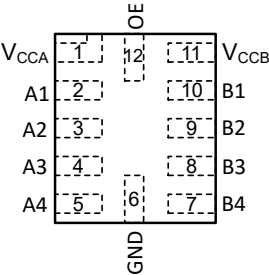


图 4-3. RUT Package, 12-Pin UQFN (Transparent Top View)

表 4-2. Pin Functions: RUT

PIN		TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.		
A1	2	I/O	Input/output A1. Referenced to V _{CCA} .
A2	3	I/O	Input/output A2. Referenced to V _{CCA} .
A3	4	I/O	Input/output A3. Referenced to V _{CCA} .
A4	5	I/O	Input/output A4. Referenced to V _{CCA} .
B1	10	I/O	Input/output B1. Referenced to V _{CCB} .
B2	9	I/O	Input/output B2. Referenced to V _{CCB} .
B3	8	I/O	Input/output B3. Referenced to V _{CCB} .
B4	7	I/O	Input/output B4. Referenced to V _{CCB} .
GND	6	—	Ground
OE	12	I	3-state output-mode enable. Pull OE low to place all outputs in 3-state mode. Referenced to V _{CCA} .
V _{CCA}	1	—	A-port supply voltage. 1.65 V ≤ V _{CCA} ≤ 3.6 V and V _{CCA} ≤ V _{CCB} .
V _{CCB}	11	—	A-port supply voltage. 1.65 V ≤ V _{CCA} ≤ 3.6 V and V _{CCA} ≤ V _{CCB} .

(1) I = input, O = output

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
Supply voltage	V _{CCA}		– 0.5	4.6	V
	V _{CCB}		– 0.5	6.5	
Input-output pin voltage, V _{IO} ⁽²⁾	A1, A2, A3, A4	A port	– 0.5	4.6	V
	B1, B2, B3, B4	B port	– 0.5	6.5	
Output voltage, V _O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	A port	– 0.5	4.6	V
		B port	– 0.5	6.5	
	Voltage range applied to any output in the high or low state ^{(2) (3)}	A port	– 0.5	V _{CCA} + 0.5	V
		B port	– 0.5	V _{CCB} + 0.5	
Input clamp current, I _{IK}		V _I < 0	– 50		mA
Output clamp current, I _{OK}		V _O < 0	– 50		mA
Continuous output current, I _O			±50		mA
Continuous current through each V _{CCA} , V _{CCB} , or GND			±100		mA
Storage temperature range, T _{stg}			– 65	150	°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V_{CCA} and V_{CCB} are provided in the recommended operating conditions table.

5.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 ⁽¹⁾	±2500
		Charged-device model (CDM), per AEC Q100-011	±1500

- (1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			V _{CCA}	V _{CCB}	MIN	MAX	UNIT
V _{CCA}	Supply voltage ⁽¹⁾				1.65	3.6	V
V _{CCB}	Supply voltage ⁽¹⁾				2.3	5.5	
V _{IH(Ax)}	High-level input voltage	A-port I/Os	1.65 to 1.95 V	2.3 to 5.5 V	V _{CCA} – 0.2	V _{CCA}	V
			2.3 to 3.6 V		V _{CCA} – 0.4	V _{CCA}	
V _{IH(Bx)}	High-level input voltage	B-port I/Os	1.65 to 3.6 V	2.3 to 5.5 V	V _{CCB} – 0.4	V _{CCB}	V
V _{IH(OE)}	High-level input voltage	OE input			V _{CCA} × 0.65	5.5	
V _{IL(Ax)}	Low-level input voltage	A-port I/Os	1.65 to 3.6 V	2.3 to 5.5 V	0	0.15	V
V _{IL(Bx)}	Low-level input voltage	B-port I/Os			0	0.15	
V _{IL(OE)}	Low-level input voltage	OE input			0	V _{CCA} × 0.35	
Δ t / Δ V _(Ax)	Input transition rise or fall rate	A-port I/Os, push-pull driving	1.65 to 3.6 V	2.3 to 5.5 V		10	ns/V
Δ t / Δ V _(Bx)	Input transition rise or fall rate	B-port I/Os, push-pull driving				10	
Δ t / Δ V _(OE)	Input transition rise or fall rate	OE input				10	

over operating free-air temperature range (unless otherwise noted)

	V_{CCA}	V_{CCB}	MIN	MAX	UNIT
T_A Operating free-air temperature			- 40	125	°C

(1) V_{CCA} must be less than or equal to V_{CCB} , and V_{CCA} must not exceed 3.6 V.

5.4 Thermal Information

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

THERMAL METRIC ⁽¹⁾	TXS0104E-Q1			UNIT
	PW (TSSOP)	BQA (WQFN)	RUT (UQFN)	
	14 PINS	14 PINS	12 PINS	
$R_{\theta JA}$ Junction-to-ambient thermal resistance	115.2	73.5	150.4	°C/W
$R_{\theta JC(top)}$ Junction-to-case (top) thermal resistance	46.2	76.9	68.6	°C/W
$R_{\theta JB}$ Junction-to-board thermal resistance	70.9	43.0	76.3	°C/W
ψ_{JT} Junction-to-top characterization parameter	3.4	4.7	2.4	°C/W
ψ_{JB} Junction-to-board characterization parameter	70.2	42.9	76.2	°C/W
$R_{\theta JC(bot)}$ Junction-to-case (bottom) thermal resistance	—	19.6	—	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

5.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted) ⁽¹⁾

PARAMETER	TEST CONDITIONS	V_{CCA}	V_{CCB}	MIN	TYP	MAX	UNIT
$V_{OH(Ax)}$ High-level output voltage, A port	$I_{OH} = -20 \mu A$, $V_{I(Bx)} \geq V_{CCB} - 0.4 V$	1.65 to 3.6 V	2.3 to 5.5 V	$V_{CCA} \times 0.75$			V
$V_{OL(Ax)}$ Low-level output voltage, A port	$I_{OL} = 1 mA$, $V_{I(Bx)} \leq 0.15 V$	1.65 to 3.6 V	2.3 to 5.5 V			0.4	V
$V_{OH(Bx)}$ High-level output voltage, B port	$I_{OH} = -20 \mu A$, $V_{I(Ax)} \geq V_{CCA} - 0.2 V$	1.65 to 3.6 V	2.3 to 5.5 V	$V_{CCB} \times 0.75$			V
$V_{OL(Bx)}$ Low-level output voltage, B port	$I_{OL} = 1 mA$, $V_{I(Ax)} \leq 0.15 V$	1.65 to 3.6 V	2.3 to 5.5 V			0.4	V
$I_{I(OE)}$ Input current, OE	$V_I = V_{CCI}$ or GND	1.65 to 3.6 V	2.3 to 5.5 V			± 2	μA
	$V_I = V_{CCI}$ or GND, $T_A = 25^\circ C$					± 1	
I_{OZ} Off-state output current, A or B port	$OE = V_{IL}$	1.65 to 3.6 V	2.3 to 5.5 V			± 3	μA
	$OE = V_{IL}$, $T_A = 25^\circ C$					± 1	
I_{CCA} Supply current, A port	$V_I = V_O = \text{Open}$, $I_O = 0$	1.65 to V_{CCB}	2.3 to 5.5 V			4	μA
		3.6 V	0			2.2	
		0	5.5 V			- 1	
I_{CCB} Supply current, B port	$V_I = V_O = \text{Open}$, $I_O = 0$	1.65 to V_{CCB}	2.3 to 5.5 V			21	μA
		3.6 V	0			- 1	
		0	5.5 V			5	
$I_{CCA} + I_{CCB}$ Supply current, A port plus B port supply current	$V_I = V_O = \text{Open}$, $I_O = 0$	1.65 V to V_{CCB}	2.3 to 5.5 V			25	μA
$C_{I(OE)}$ Input capacitance, OE		3.3 V	3.3 V			4	pF
	$T_A = 25^\circ C$				2.5		
$C_{IO(Ax)}$ Input-output capacitance, A port		3.3 V	3.3 V			6.5	pF
	$T_A = 25^\circ C$				5		
$C_{IO(Bx)}$ Input-output capacitance, B port						16.5	
	$T_A = 25^\circ C$				12		

(1) V_{CCA} must be less than or equal to V_{CCB} , and V_{CCA} must not exceed 3.6 V.

5.6 Timing Requirements— $V_{CCA} = 1.8\text{ V} \pm 0.15\text{ V}$

over recommended operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
Data rate	Push-pull driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		18	Mbps
		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		21	
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		23	
	Open-drain driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		2	
		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		2	
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		2	
t_w Pulse duration, data inputs See 图 6-4	Push-pull driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	55		ns
		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	47		
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$	43		
	Open-drain driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	500		
		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	500		
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$	500		

5.7 Timing Requirements— $V_{CCA} = 2.5\text{ V} \pm 0.2\text{ V}$

over recommended operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
Data rate	Push-pull driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		20	Mbps
		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		22	
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		24	
	Open-drain driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		2	
		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		2	
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		2	
t_w Pulse duration, data inputs See 图 6-4	Push-pull driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	50		ns
		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	45		
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$	41		
	Open-drain driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	500		
		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	500		
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$	500		

5.8 Timing Requirements— $V_{CCA} = 3.3\text{ V} \pm 0.3\text{ V}$

over recommended operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
Data rate	Push-pull driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		22	Mbps
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		24	
	Open-drain driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		2	
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		2	
t_w Pulse duration, Data inputs See 图 6-4	Push-pull driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	45		ns
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$	41		
	Open-drain driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	500		
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$	500		

5.9 Switching Characteristics— $V_{CCA} = 1.8 \text{ V} \pm 0.15 \text{ V}$

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	MAX	UNIT
$t_{PHL(A-B)}$	Propagation delay time (high to low), from A (input) to B (output) See 图 6-5	Push-pull driving	$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		6	ns
			$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		5.8	
			$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		5.8	
	Open-drain driving		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		8.8	
			$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		9.6	
			$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		10	
$t_{PHL(B-A)}$	Propagation delay time (high to low), from B (input) to A (output) See 图 6-5	Push-pull driving	$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		4.4	ns
			$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		4.5	
			$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		4.7	
	Open-drain driving		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		5.3	
			$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		4.4	
			$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		4	
$t_{PLH(A-B)}$	Propagation delay time (low to high), from A (input) to B (output) See 图 6-5	Push-pull driving	$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		7.7	ns
			$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		6.8	
			$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		7	
	Open-drain driving		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		50	
			$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		26	
			$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		33	
$t_{PLH(B-A)}$	Propagation delay time (low to high), from B (input) to A (output) See 图 6-5	Push-pull driving	$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		5.3	ns
			$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		4.5	
			$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		0.5	
	Open-drain driving		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		36	
			$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		16	
			$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		20	
$t_{en(OE-A)}$ $t_{en(OE-B)}$	Enable time, from OE (input) to A or B (output)	$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$			200	ns
		$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$			200	
		$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$			200	
$t_{dis(OE-A)}$ $t_{dis(OE-B)}$	Disable time, from OE (input) to A or B (output)	$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$			200	ns
		$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$			200	
		$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$			200	
$t_{r(Ax)}$	Rise time, A port	Push-pull driving	$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		9.5	ns
			$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		9.3	
			$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		15	
	Open-drain driving		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	38	199	
			$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	30	150	
			$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	22	109	
$t_{r(Bx)}$	Rise time, B port	Push-pull driving	$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		10.8	ns
			$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		9.1	
			$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		7.6	
	Open-drain driving		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	34	186	
			$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	23	112	
			$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	10	58	

5.9 Switching Characteristics— $V_{CCA} = 1.8\text{ V} \pm 0.15\text{ V}$ (续)

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	MAX	UNIT
$t_{f(Ax)}$	Fall time, A port	Push-pull driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		5.9	ns
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		6	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		13.3	
	Open-drain driving		$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		6.9	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		6.4	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		6.1	
$t_{f(Bx)}$	Fall time, B port	Push-pull driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		7.6	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		7.5	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		8.8	
	Open-drain driving		$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		13.8	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		16.2	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		16.2	
t_{sk}	Channel-to-channel skew	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$			1	ns
		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$			1	
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$			1	
	Maximum data rate	Push-pull driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		18	Mbps
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		21	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		23	
		Open-drain driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		2	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		2	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		2	

5.10 Switching Characteristics— $V_{CCA} = 2.5\text{ V} \pm 0.2\text{ V}$

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	MAX	UNIT
$t_{PHL(A-B)}$	Propagation delay time (high to low), from A (input) to B (output) See 图 6-5	Push-pull driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		3.2	ns
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		3.3	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		3.4	
	Open-drain driving		$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		6.3	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		6	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		5.8	
$t_{PHL(B-A)}$	Propagation delay time (high to low), from B (input) to A (output) See 图 6-5	Push-pull driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		3	ns
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		3.6	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		4.3	
	Open-drain driving		$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		4.7	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		4.2	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		4	
$t_{PLH(A-B)}$	Propagation delay time (low to high), from A (input) to B (output) See 图 6-5	Push-pull driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		3.5	ns
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		4.1	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		4.4	
	Open-drain driving		$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		3.5	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		4.1	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		4.4	
$t_{PLH(B-A)}$	Propagation delay time (low to high), from B (input) to A (output) See 图 6-5	Push-pull driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		2.5	ns
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		1.6	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		0.7	
	Open-drain driving		$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		2.5	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		1.6	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		1	
$t_{en(OE-A)}$ $t_{en(OE-B)}$	Enable time, from OE (input) to A or B (output)	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$			200	ns
		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$			200	
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$			200	
$t_{dis(OE-A)}$ $t_{dis(OE-B)}$	Disable time, from OE (input) to A or B (output)	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$			200	ns
		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$			200	
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$			200	
$t_{r(Ax)}$	Rise time, A port	Push-pull driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		7.4	ns
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		6.6	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		5.6	
	Open-drain driving		$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	34	180	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	28	150	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$	24	105	
$t_{r(Bx)}$	Rise time, B port	Push-pull driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		8.3	ns
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		7.2	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		6.1	
	Open-drain driving		$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	35	170	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	24	120	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$	12	64	

5.10 Switching Characteristics— $V_{CCA} = 2.5\text{ V} \pm 0.2\text{ V}$ (续)

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	MAX	UNIT
$t_{f(Ax)}$	Fall time, A port	Push-pull driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		5.7	ns
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		5.5	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		5.3	
	Open-drain driving		$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$			
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$			
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		5.8	
$t_{f(Bx)}$	Fall time, B port	Push-pull driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		7.8	ns
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		6.7	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		6.6	
	Open-drain driving		$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		8.8	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		9.4	
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		10.4	
t_{sk}	Channel-to-channel skew	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$			1	ns
		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$			1	
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$			1	
	Maximum data rate	Push-pull driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	20		Mbps
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	22		
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$	24		
		Open-drain driving	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	2		
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	2		
			$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$	2		

5.11 Switching Characteristics— $V_{CCA} = 3.3\text{ V} \pm 0.3\text{ V}$

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	MAX	UNIT
$t_{PHL(A-B)}$ Propagation delay time (high to low), from A (input) to B (output) See 图 6-5	Push-pull driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		2.4	ns
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		3.1	
	Open-drain driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		4.2	
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		4.6	
$t_{PHL(B-A)}$ Propagation delay time (high to low), from B (input) to A (output) See 图 6-5	Push-pull driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		2.5	ns
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		3.3	
	Open-drain driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		124	
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		97	
$t_{PLH(A-B)}$ Propagation delay time (low to high), from A (input) to B (output) See 图 6-5	Push-pull driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		4.2	ns
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		4.4	
	Open-drain driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		4.2	
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		4.4	
$t_{PLH(B-A)}$ Propagation delay time (low to high), from B (input) to A (output) See 图 6-5	Push-pull driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		2.5	ns
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		2.6	
	Open-drain driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		2.5	
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		3.3	
$t_{en(OE-A)}$ Enable time, from OE (input) to A or B (output)	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$			200	ns
	$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$			200	
$t_{dis(OE-A)}$ Disable time, from OE (input) to A or B (output)	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$			200	ns
	$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$			200	
$t_{r(Ax)}$ Rise time, A port	Push-pull driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		5.6	ns
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		5	
	Open-drain driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	25	140	
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$	19	102	
$t_{r(Bx)}$ Rise time, B port	Push-pull driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		6.4	ns
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		7.4	
	Open-drain driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	26	130	
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$	14	75	
$t_{f(Ax)}$ Fall time, A port	Push-pull driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		5.4	ns
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		5	
	Open-drain driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		6.1	
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		5.7	
$t_{f(Bx)}$ Fall time, B port	Push-pull driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		7.4	ns
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		7.6	
	Open-drain driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		7.6	
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		8.3	
t_{sk} Channel-to-channel skew	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$			1	ns
	$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$			1	
Maximum data rate	Push-pull driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	22		Mbps
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$	24		
	Open-drain driving	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	2		
		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$	2		

5.12 Typical Characteristics

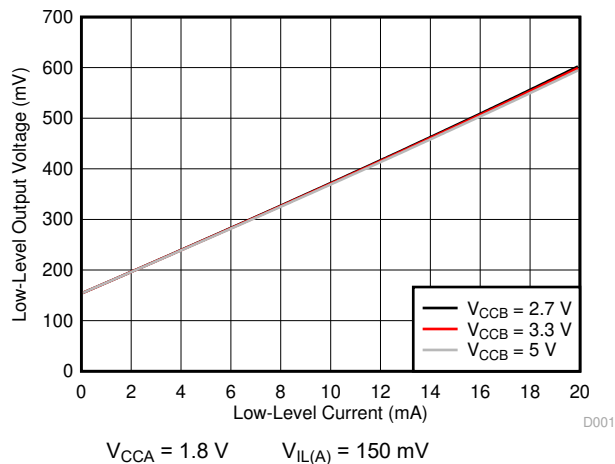


图 5-1. Low-Level Output Voltage ($V_{OL(Ax)}$) vs Low-Level Current ($I_{OL(Ax)}$)

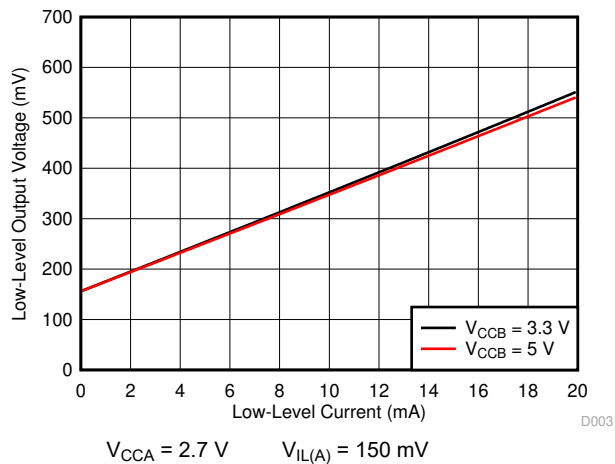


图 5-2. Low-Level Output Voltage ($V_{OL(Ax)}$) vs Low-Level Current ($I_{OL(Ax)}$)

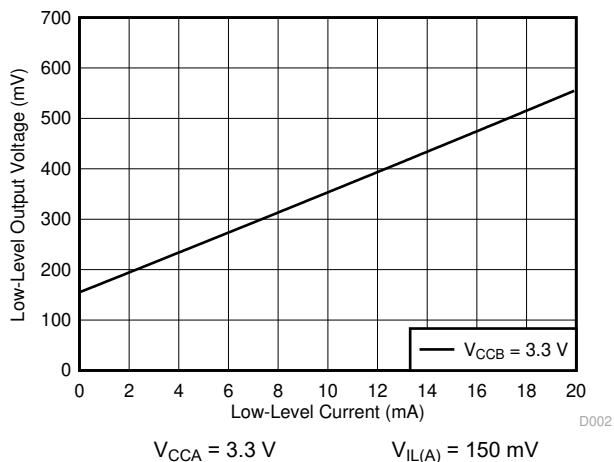


图 5-3. Low-Level Output Voltage ($V_{OL(Ax)}$) vs Low-Level Current ($I_{OL(Ax)}$)

6 Parameter Measurement Information

6.1 Load Circuits

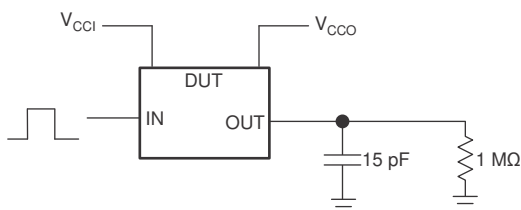


图 6-1. Data Rate, Pulse Duration, Propagation Delay, Output Rise-Time and Fall-Time Measurement Using a Push-Pull Driver

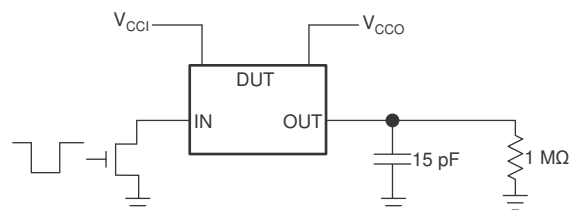
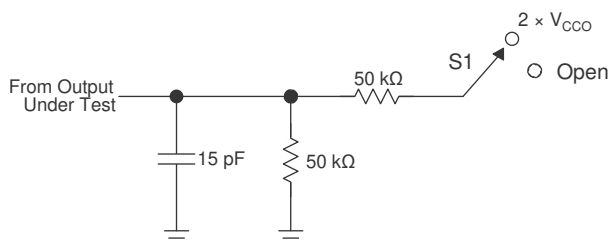


图 6-2. Data Rate, Pulse Duration, Propagation Delay, Output Rise-Time and Fall-Time Measurement Using an Open-Drain Driver



TEST	S1
t_{PZL} / t_{PLZ} (t_{dis})	$2 \times V_{CCO}$
t_{PHZ} / t_{PZH} (t_{en})	Open

图 6-3. Load Circuit for Enable-Time and Disable-Time Measurement

1. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
2. t_{PZL} and t_{PZH} are the same as t_{en} .
3. V_{CCI} is the V_{CC} associated with the input port.
4. V_{CCO} is the V_{CC} associated with the output port.

6.2 Voltage Waveforms

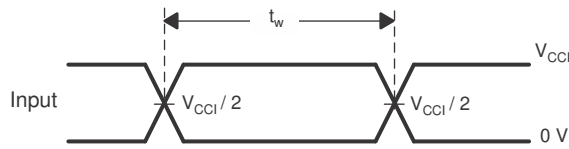


图 6-4. Pulse Duration

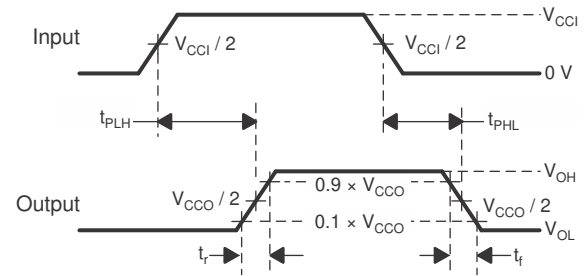
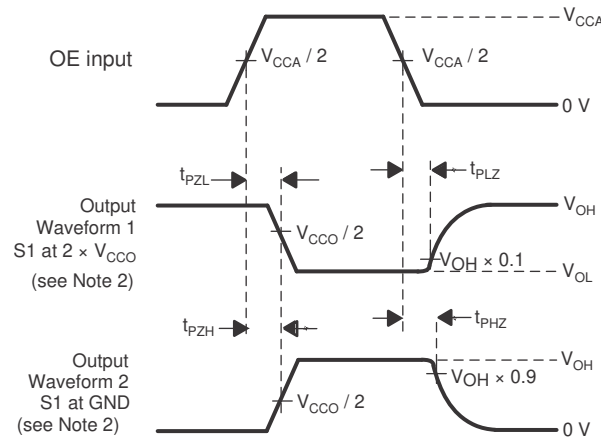


图 6-5. Propagation Delay Times



1. C_L includes probe and jig capacitance.
2. Waveform 1 in 图 6-6 is for an output with internal such that the output is high, except when OE is high (see 图 6-3). Waveform 2 in 图 6-6 is for an output with conditions such that the output is low, except when OE is high.
3. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $dv/dt \geq 1$ V/ns.
4. The outputs are measured one at a time, with one transition per measurement.
5. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
6. t_{PZL} and t_{PZH} are the same as t_{en} .
7. t_{PLH} and t_{PHL} are the same as t_{pd} .
8. V_{CCI} is the V_{CC} associated with the input port.
9. V_{CCO} is the V_{CC} associated with the output port.

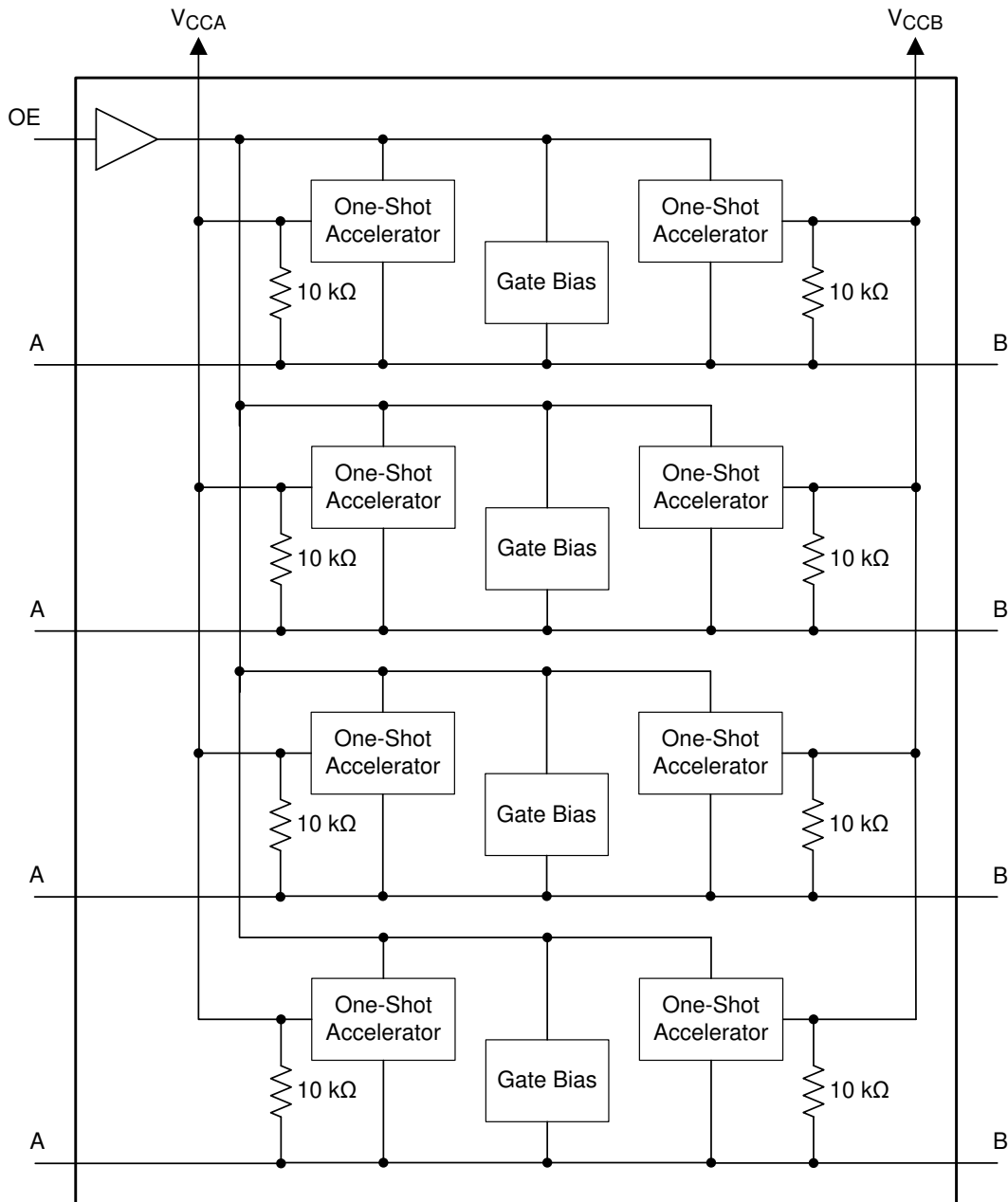
图 6-6. Enable and Disable Times

7 Detailed Description

7.1 Overview

The TXS0104E-Q1 device is a directionless voltage-level translator specifically designed for translating logic voltage levels. The A port is able to accept I/O voltages ranging from 1.65 V to 3.6 V, while the B port can accept I/O voltages from 2.3 V to 5.5 V. The device is a pass gate architecture with edge rate accelerators (one shots) to improve the overall data rate. 10-k Ω pullup resistors, commonly used in open drain applications, have been conveniently integrated so that an external resistor is not needed. While this device is designed for open drain applications, the device can also translate push-pull CMOS logic outputs.

7.2 Functional Block Diagram



Copyright © 2016, Texas Instruments Incorporated

7.3 Feature Description

7.3.1 Architecture

The TXS0104E-Q1 architecture (see 图 7-1) does not require a direction-control signal in order to control the direction of data flow from A to B or from B to A.

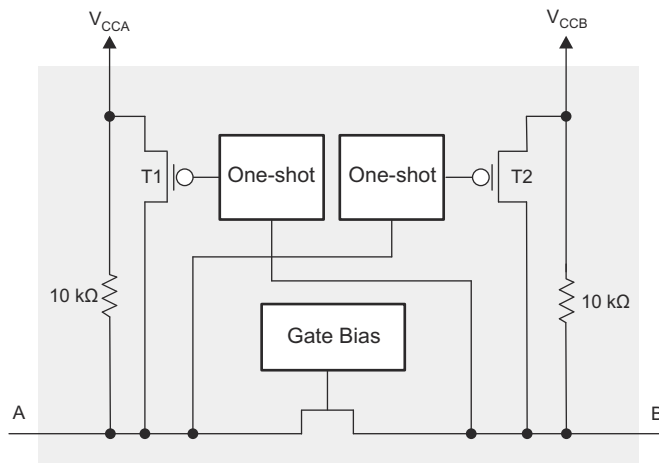


图 7-1. Architecture of a TXS01xx Cell

Each A-port I/O has an internal 10-kΩ pullup resistor to V_{CCA} , and each B-port I/O has an internal 10-kΩ pullup resistor to V_{CCB} . The output one-shots detect rising edges on the A or B ports. During a rising edge, the one-shot turns on the PMOS transistors (T1, T2) for a short duration which speeds up the low-to-high transition.

7.3.2 Input Driver Requirements

The fall time (t_{fA} , t_{fB}) of a signal depends on the output impedance of the external device driving the data I/Os of the TXS0104E-Q1 device. Similarly, the t_{PHL} and maximum data rates also depend on the output impedance of the external driver. The values for t_{fA} , t_{fB} , t_{PHL} , and maximum data rates in the data sheet assume that the output impedance of the external driver is less than 50 Ω.

7.3.3 Power Up

During operation, ensure that $V_{CCA} \leq V_{CCB}$ at all times. During power-up sequencing, $V_{CCA} \geq V_{CCB}$ does not damage the device, so any power supply can be ramped up first.

7.3.4 Enable and Disable

The TXS0104E-Q1 device has an OE input that disables the device by setting OE low, which places all I/Os in the high-impedance state. The disable time (t_{dis}) indicates the delay between the time when the OE pin goes low and when the outputs actually enter the high-impedance state. The enable time (t_{en}) indicates the amount of time the user must allow for the one-shot circuitry to become operational after the OE pin is taken high.

7.3.5 Pull Up and Pull Down Resistors on I/O Lines

Each A-port I/O has an internal 10-kΩ pullup resistor to V_{CCA} , and each B-port I/O has an internal 10-kΩ pullup resistor to V_{CCB} . If a smaller value of pullup resistor is required, an external resistor must be added from the I/O to V_{CCA} or V_{CCB} (in parallel with the internal 10-kΩ resistors).

7.4 Device Functional Modes

The TXS0104E-Q1 device has two functional modes, enabled and disabled. To disable the device set the OE input low, which places all I/Os in a high impedance state. Setting the OE input high will enable the device.

8 Application and Implementation

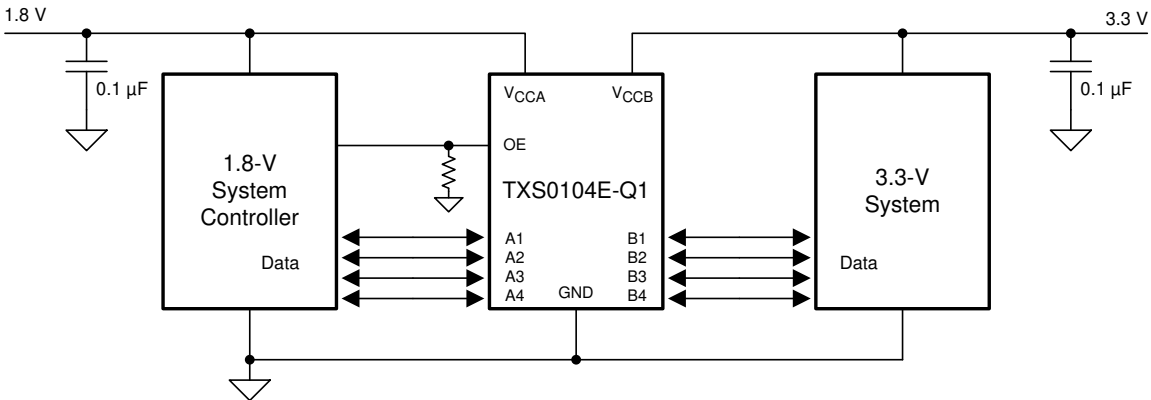
备注

以下应用部分中的信息不属于 TI 器件规格的范围，TI 不担保其准确性和完整性。TI 的客户应负责确定器件是否适用于其应用。客户应验证并测试其设计，以确保系统功能。

8.1 Application Information

The TXS0104E-Q1 device can be used in level-translation applications for interfacing devices or systems operating at different interface voltages with one another. The TXS0104E-Q1 device is optimal for use in applications where an open-drain driver is connected to the data I/Os. The TXS0104E-Q1 device can also be used in applications where a push-pull driver is connected to the data I/Os, but the TXB0104-Q1 device might be a better option for such push-pull applications.

8.2 Typical Application



Copyright © 2016, Texas Instruments Incorporated

图 8-1. Application Schematic

8.2.1 Design Requirements

For this design example, use the parameters listed in 表 8-1.

表 8-1. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
Input voltage range	1.65 to 3.6 V
Output voltage range	2.3 to 5.5 V

8.2.2 Detailed Design Procedure

To begin the design process, determine the following:

- Input voltage range
 - Use the supply voltage of the device that is driving the TXS0104E-Q1 device to determine the input voltage range. For a valid logic high the value must exceed the V_{IH} of the input port. For a valid logic low the value must be less than the V_{IL} of the input port.
- Output voltage range
 - Use the supply voltage of the device that the TXS0104E-Q1 device is driving to determine the output voltage range.
 - The TXS0104E-Q1 device has 10-k Ω internal pullup resistors. External pullup resistors can be added to reduce the total RC of a signal trace if necessary.

- An external pull down resistor decreases the output V_{OH} and V_{OL} . Use 方程式 1 to calculate the V_{OH} as a result of an external pull down resistor.

$$V_{OH} = V_{CCx} \times R_{PD} / (R_{PD} + 10\text{ k}\Omega) \quad (1)$$

where

- V_{CCx} is the supply voltage on either V_{CCA} or V_{CCB}
- R_{PD} is the value of the external pull down resistor

8.2.3 Application Curve

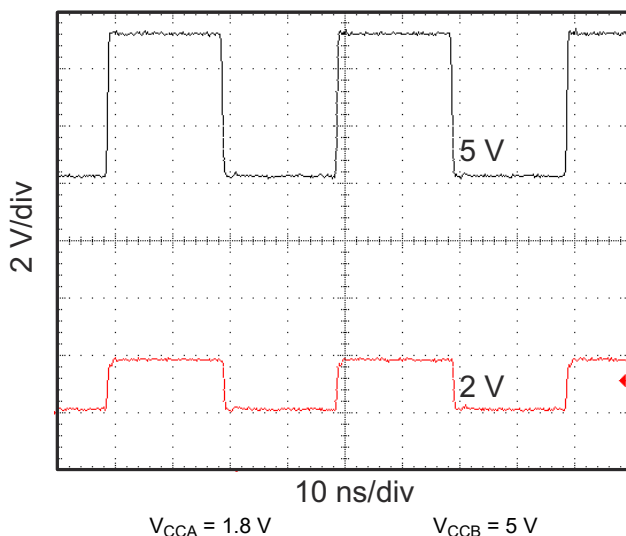


图 8-2. Level-Translation of a 2.5-MHz Signal

8.3 Power Supply Recommendations

The TXS0104E-Q1 device uses two separate configurable power-supply rails, V_{CCA} and V_{CCB} . V_{CCB} accepts any supply voltage from 2.3 V to 5.5 V and V_{CCA} accepts any supply voltage from 1.65 V to 3.6 V as long as V_S is less than or equal to V_{CCB} . The A port and B port are designed to track V_{CCA} and V_{CCB} respectively allowing for low-voltage bidirectional translation between any of the 1.8-V, 2.5-V, 3.3-V, and 5-V voltage nodes.

The TXS0104E-Q1 device does not require power sequencing between V_{CCA} and V_{CCB} during power-up so the power-supply rails can be ramped in any order. A V_{CCA} value greater than or equal to V_{CCB} ($V_{CCA} \geq V_{CCB}$) does not damage the device, but during operation, V_{CCA} must be less than or equal to V_{CCB} ($V_{CCA} \leq V_{CCB}$) at all times.

The output-enable (OE) input circuit is designed so that it is supplied by V_{CCA} and when the (OE) input is low, all outputs are placed in the high-impedance state. To enable the high-impedance state of the outputs during power up or power down, the OE input pin must be tied to GND through a pull down resistor and must not be enabled until V_{CCA} and V_{CCB} are fully ramped and stable. The minimum value of the pull down resistor to ground is determined by the current-sourcing capability of the driver.

8.4 Layout

8.4.1 Layout Guidelines

For reliability of the device, following common printed-circuit board layout guidelines is recommended.

- Bypass capacitors should be used on power supplies.
- Short trace lengths should be used to avoid excessive loading.
- PCB signal trace-lengths must be kept short enough so that the round-trip delay of any reflection is less than the one shot duration, approximately 30 ns, ensuring that any reflection encounters low impedance at the source driver.
- Placing pads on the signal paths for loading capacitors or pullup resistors to help adjust rise and fall times of signals depending on the system requirements

8.4.2 Layout Example

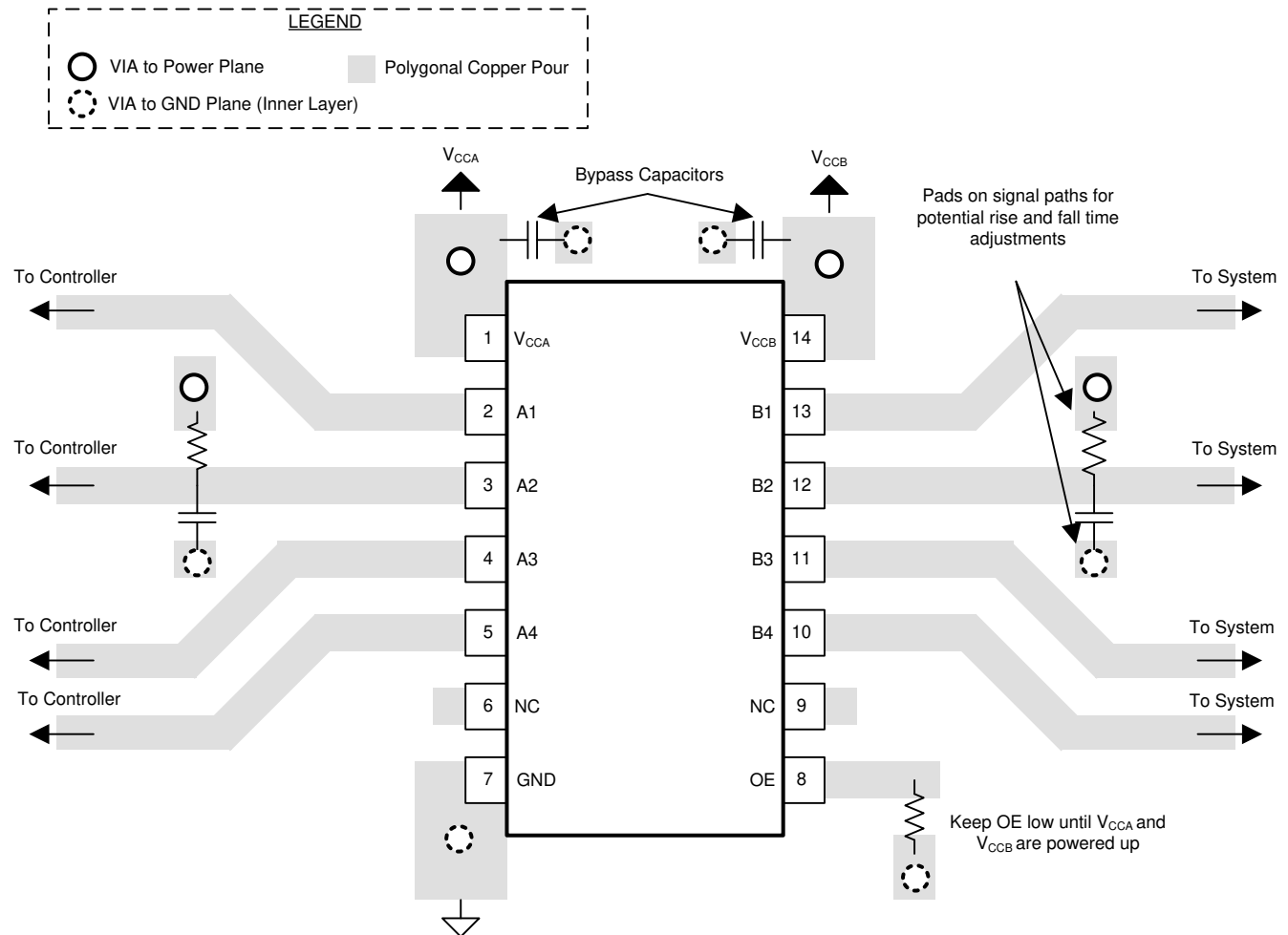


图 8-3. TXS0104E-Q1 Layout Example

9 Device and Documentation Support

9.1 Documentation Support

9.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, [Introduction to Logic application note](#)

9.2 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击 [通知](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

9.3 支持资源

TI E2E™ 中文支持论坛是工程师的重要参考资料，可直接从专家处获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题，获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的[使用条款](#)。

9.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

所有商标均为其各自所有者的财产。

10 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

11 术语表

TI 术语表 本术语表列出并解释了术语、首字母缩略词和定义。

12 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision E (October 2023) to Revision F (October 2024)	Page
• Updated thermal values for new packages.....	6
Changes from Revision D (January 2017) to Revision E (October 2023)	Page
• 向数据表添加了 <i>RUT</i> 封装信息.....	1
Changes from Revision C (January 2017) to Revision D (June 2023)	Page
• 更新了整个文档中的表格、图和交叉参考的编号格式.....	1
• 向数据表添加了 <i>BQA</i> 封装信息.....	1

Changes from Revision B (May 2014) to Revision C (January 2017)	Page
• Changed the type of the OE pin from output (O) to input (I) in the <i>Pin Functions</i> table.....	3
• Moved T_{stg} back to the <i>Absolute Maximum Ratings</i> table and changed the <i>Handling Ratings</i> table to <i>ESD Ratings</i>	5

Changes from Revision A (April 2014) to Revision B (May 2014)	Page
• 将器件状态从产品预发布 更改为量产数据	1

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TXS0104EQPWRQ1	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	04EQ1
TXS0104EQRUTRQ1	Active	Production	UQFN (RUT) 12	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	1RQ
TXS0104EQWBQARQ1	Active	Production	WQFN (BQA) 14	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	YF04EQ

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TXS0104E-Q1 :

- Catalog : [TXS0104E](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TXS0104EQPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TXS0104EQRUTRQ1	UQFN	RUT	12	3000	180.0	8.4	2.0	2.3	0.75	4.0	8.0	Q1
TXS0104EQWBQARQ1	WQFN	BQA	14	3000	180.0	12.4	2.8	3.3	1.1	4.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TXS0104EQPWRQ1	TSSOP	PW	14	2000	356.0	356.0	35.0
TXS0104EQRUTRQ1	UQFN	RUT	12	3000	210.0	185.0	35.0
TXS0104EQWBQARQ1	WQFN	BQA	14	3000	210.0	185.0	35.0

GENERIC PACKAGE VIEW

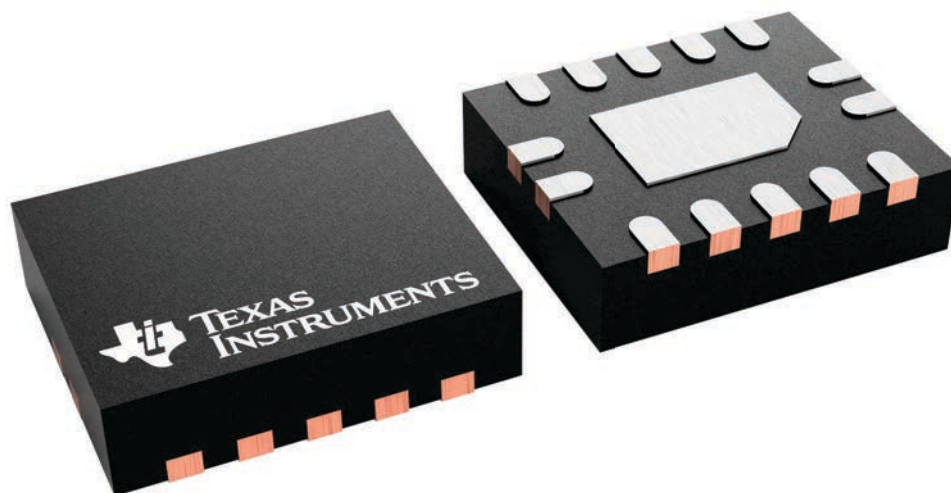
BQA 14

WQFN - 0.8 mm max height

2.5 x 3, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



WQFN - 0.8 mm max height

Technical drawing of a microelectronic package showing top, side, and cross-sectional views with dimensions and callouts.

Top View:

- Overall width: 2.6
- Overall height: 3.1
- PIN 1 INDEX AREA (indicated by a shaded square)
- Section A-A is indicated by a line with arrows.

Side View:

- Overall height: 2.9
- Seating Plane is indicated.
- Dimension 0.08 C is shown for the seating plane area.

Cross-Section A-A (TYPICAL):

- Shows the internal structure and the seating plane.
- Dimension 0.1 MIN is shown for the thickness of the seating plane.
- Dimension (0.13) is shown for the width of the seating plane.

Bottom View:

- Overall width: 2.6
- Overall height: 3.1
- Exposed Thermal Pad is indicated.
- Section A-A is indicated by a line with arrows.
- Dimension 0.05 is shown for the thickness of the exposed thermal pad.
- Dimension 0.00 is shown for the thickness of the exposed thermal pad.
- Dimension 0.8 is shown for the thickness of the exposed thermal pad.
- Dimension 0.6 is shown for the thickness of the exposed thermal pad.
- Dimension 1 ± 0.1 is shown for the width of the exposed thermal pad.
- Dimension 2X 0.5 is shown for the width of the exposed thermal pad.
- Dimension 7 is shown for the width of the exposed thermal pad.
- Dimension 8 is shown for the width of the exposed thermal pad.
- Dimension 9 is shown for the width of the exposed thermal pad.
- Dimension 15 is shown for the width of the exposed thermal pad.
- Dimension 13 is shown for the width of the exposed thermal pad.
- Dimension 14X 0.3 is shown for the width of the exposed thermal pad.
- Dimension 14X 0.2 is shown for the width of the exposed thermal pad.
- Dimension 0.1 M is shown for the width of the exposed thermal pad.
- Dimension 0.05 M is shown for the width of the exposed thermal pad.
- Dimension 0.16 TYP is shown for the width of the exposed thermal pad.
- Dimension (0.2) TYP is shown for the width of the exposed thermal pad.

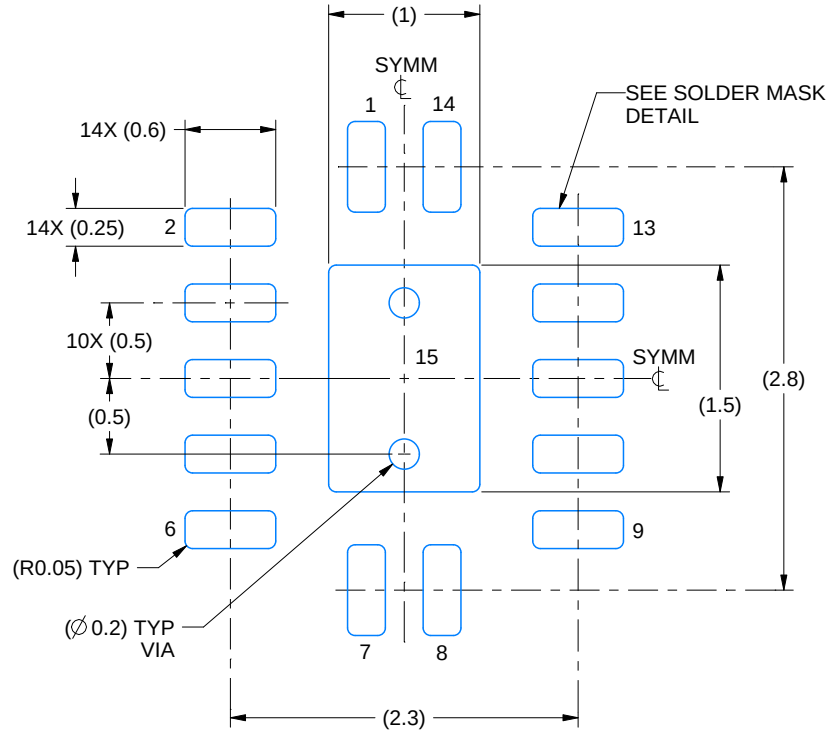
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

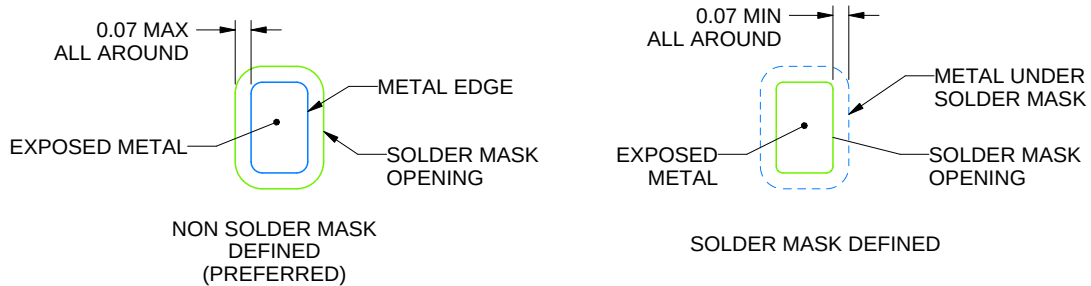
BQA0014B

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X



SOLDER MASK DETAILS

4227062/B 09/2021

NOTES: (continued)

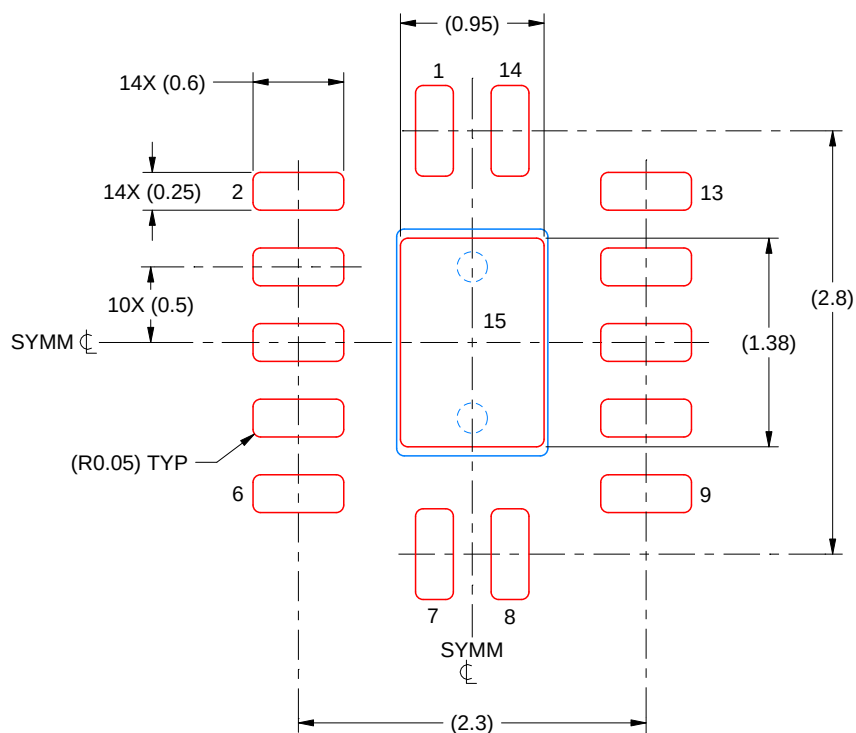
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

BQA0014B

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



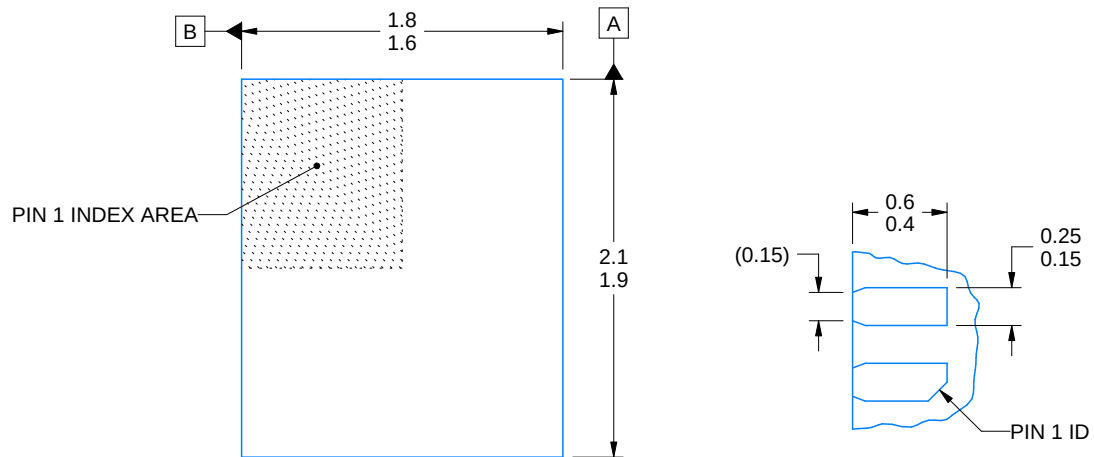
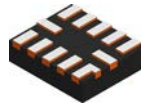
SOLDER PASTE EXAMPLE
BASED ON 0.125 MM THICK STENCIL
SCALE: 20X

EXPOSED PAD 15
87% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

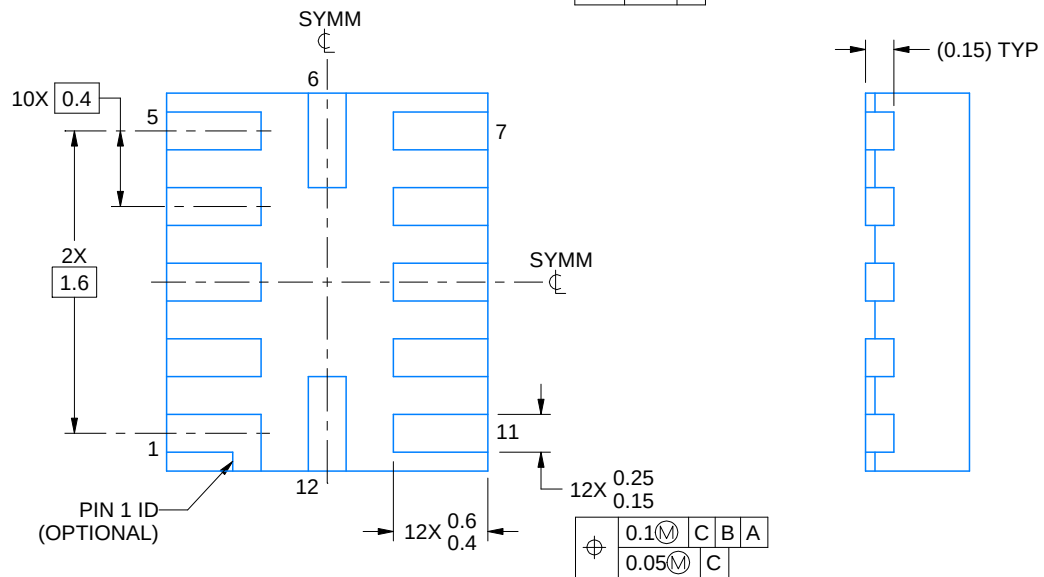
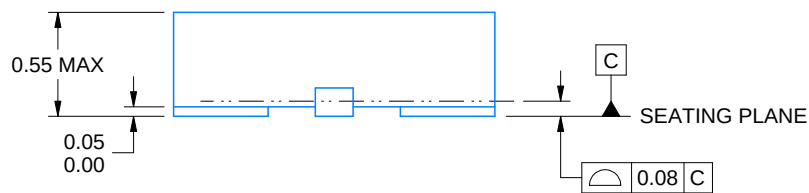
4227062/B 09/2021

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



OPTIONAL TERMINAL & PIN 1 ID



4220310/A 11/2016

NOTES:

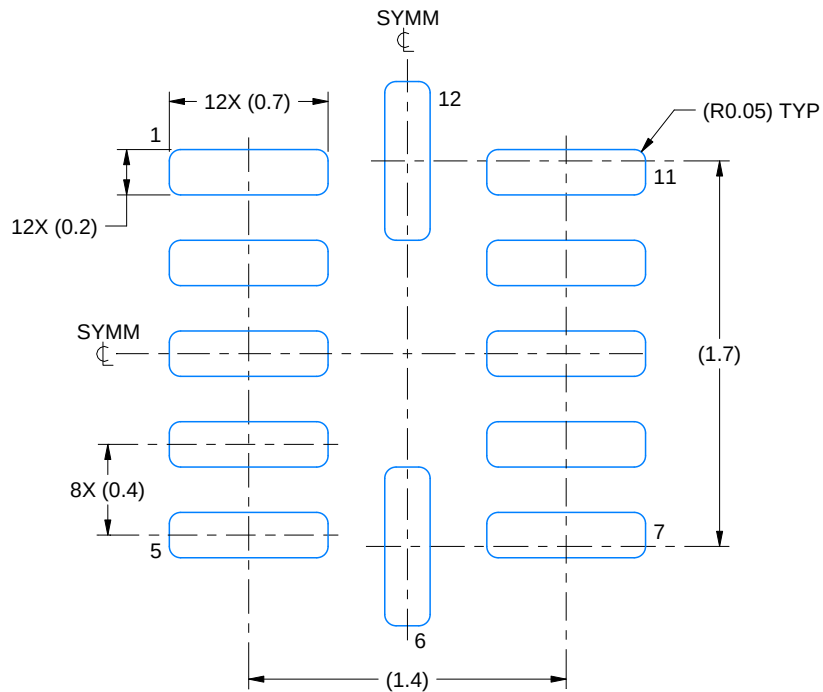
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

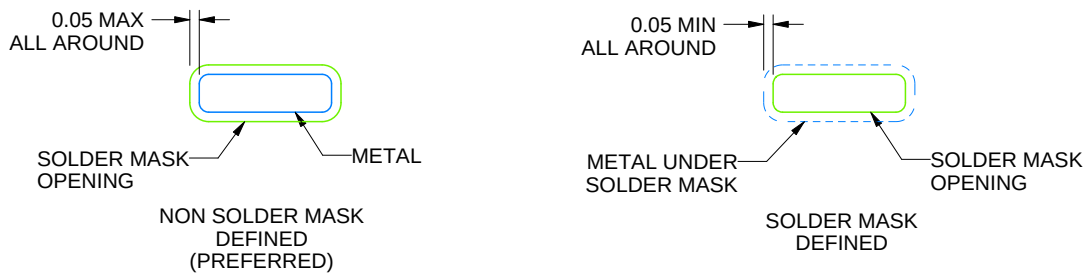
RUT0012A

UQFN - 0.55 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
SCALE:30X



SOLDER MASK DETAILS

4220310/A 11/2016

NOTES: (continued)

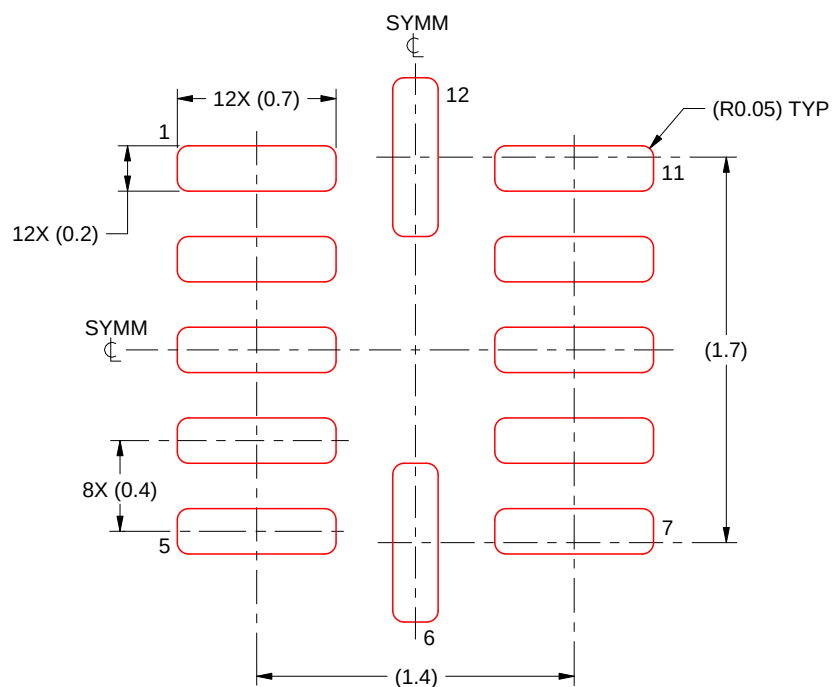
3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).

EXAMPLE STENCIL DESIGN

RUT0012A

UQFN - 0.55 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

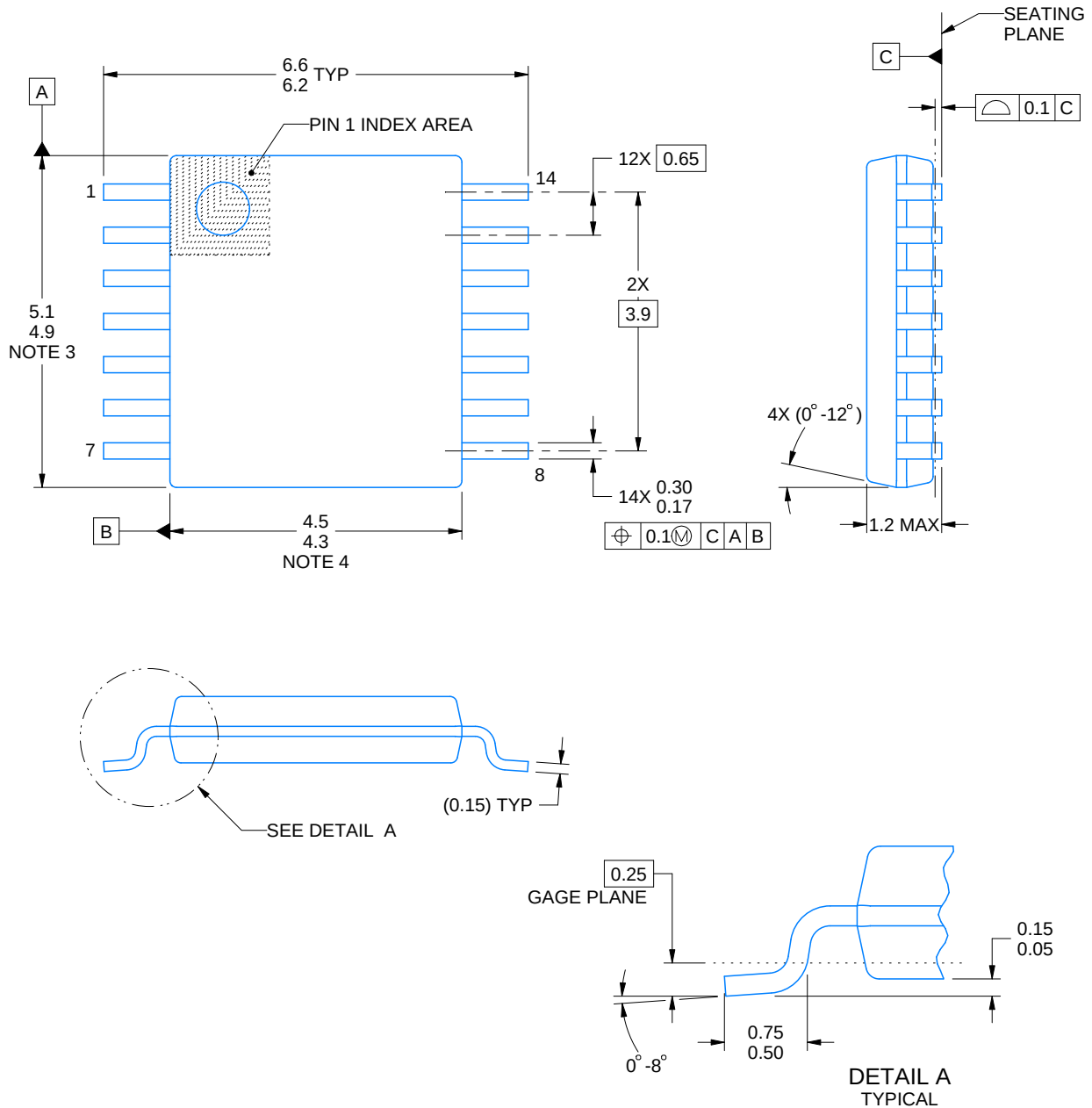
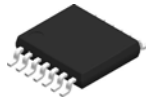


SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE: 30X

4220310/A 11/2016

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



4220202/B 12/2023

NOTES:

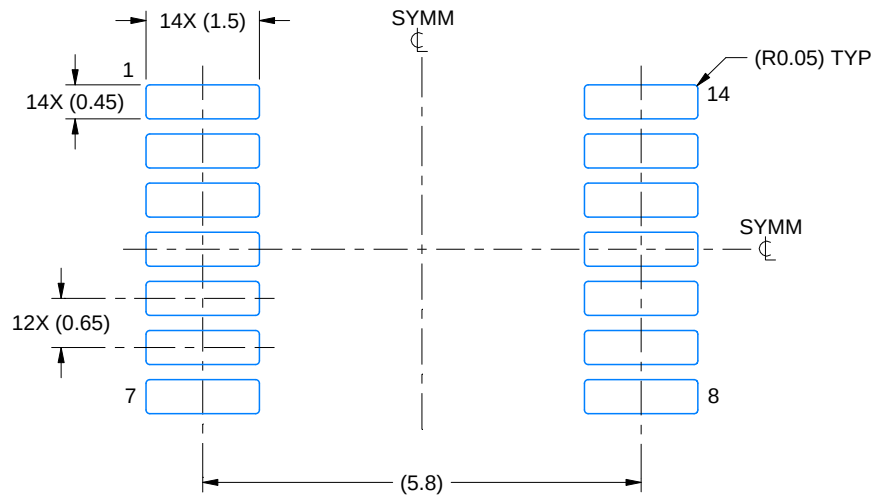
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

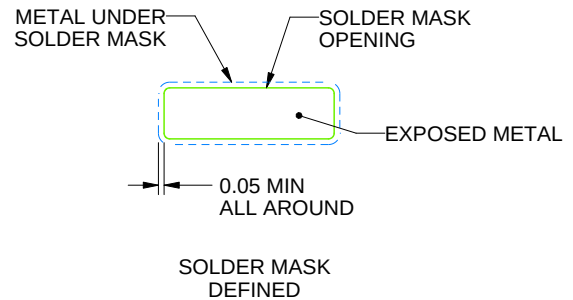
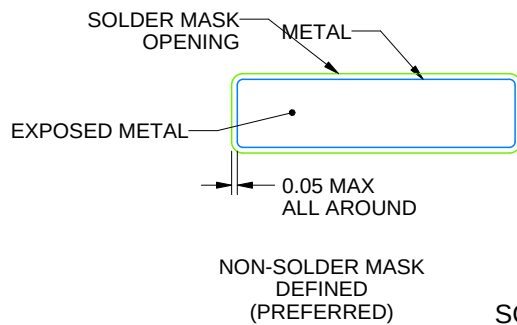
PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220202/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

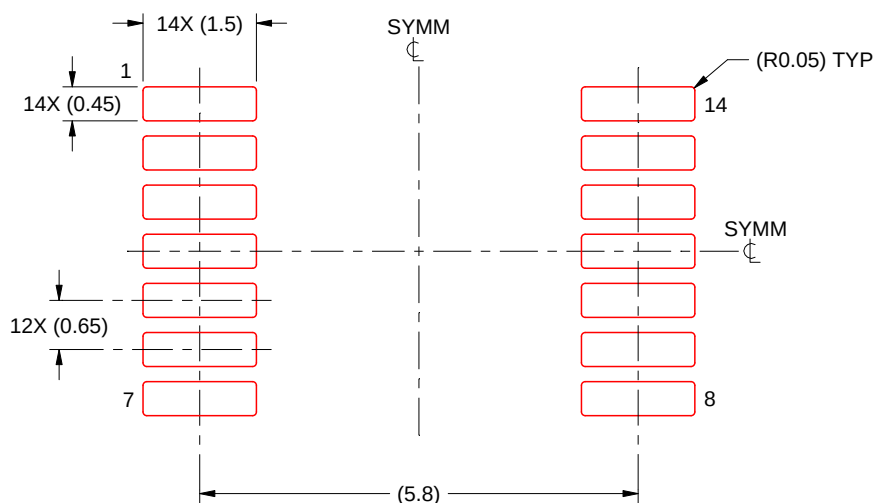
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

重要通知和免责声明

TI“按原样”提供技术和可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证没有瑕疵且不做任何明示或暗示的担保，包括但不限于对适销性、某特定用途方面的适用性或不侵犯任何第三方知识产权的暗示担保。

这些资源可供使用 TI 产品进行设计的熟练开发人员使用。您将自行承担以下全部责任：(1) 针对您的应用选择合适的 TI 产品，(2) 设计、验证并测试您的应用，(3) 确保您的应用满足相应标准以及任何其他功能安全、信息安全、监管或其他要求。

这些资源如有变更，恕不另行通知。TI 授权您仅可将这些资源用于研发本资源所述的 TI 产品的相关应用。严禁以其他方式对这些资源进行复制或展示。您无权使用任何其他 TI 知识产权或任何第三方知识产权。您应全额赔偿因在这些资源的使用中对 TI 及其代表造成的任何索赔、损害、成本、损失和债务，TI 对此概不负责。

TI 提供的产品受 [TI 的销售条款](#) 或 [ti.com](#) 上其他适用条款/TI 产品随附的其他适用条款的约束。TI 提供这些资源并不会扩展或以其他方式更改 TI 针对 TI 产品发布的适用的担保或担保免责声明。

TI 反对并拒绝您可能提出的任何其他或不同的条款。

邮寄地址：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
版权所有 © 2025，德州仪器 (TI) 公司